

<u>CY2313ANZ</u>

13 Output, 3.3V SDRAM Buffer for Desktop PCs with 3 DIMMs

Features

- · One input to 13 output buffer/driver
- · Supports up to three SDRAM DIMMs
- One additional outputs for feedback
- I²C[™] interface for output control
- · Low skew outputs
- Up to 100 MHz operation
- Multiple V_{DD} and V_{SS} pins for noise reduction
- Low EMI outputs
- · 28-pin SOIC (300-mil) package
- 3.3V operation

Functional Description

The CY2313ANZ is a 3.3V buffer designed to distribute high-speed clocks in desktop PC applications. The part has 13 outputs, 12 of which can be used to drive up to three SDRAM DIMMs, and the remaining can be used for external feedback to a PLL. The device operates at 3.3V and outputs can run up to 100 MHz, thus making it compatible with Pentium® II processors. The CY2313ANZ can be used in conjunction with the CY2280, CY2281, CY2282 or similar clock synthesizer for a complete Pentium II motherboard solution.

The CY2313ANZ also includes an I²C interface which can enable or disable each output clock. On power-up, all output clocks are enabled.



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Pin Summary

Name	Pins	Description
V _{DD}	1, 5, 20, 24, 28	3.3V Digital voltage supply
V _{SS}	4, 8, 17, 21, 25	Ground
V _{DDIIC}	13	I ² C Voltage supply
V _{SSIIC}	16	Ground for I ² C
BUF_IN	9	Input clock
SDATA	14	I ² C data input, internal pull-up to V _{DD}
SCLK	15	I ² C clock input, internal pull-up to V _{DD}
SDRAM [0-12]	2, 3, 6, 7, 10, 11, 12, 18, 19, 22, 23, 26, 27	SDRAM clock outputs

Serial Configuration Map

• The Serial bits will be read by the clock driver in the following order:

Byte 0 - Bits 7, 6, 5, 4, 3, 2, 1, 0 Byte 1 - Bits 7, 6, 5, 4, 3, 2, 1, 0

Byte N - Bits 7, 6, 5, 4, 3, 2, 1, 0

- Reserved and unused bits should be programmed to "0"
- I²C Address for the CY2313ANZ is:

A6	A5	A4	A3	A2	A1	A0	R/W
1	1	0	1	0	0	1	

Byte 0:SDRAM Active/Inactive Register (1 = Enable, 0 = Disable), Default = Enabled

Bit	Pin #	Description			
Bit 7	11	SDRAM5 (Active/Inactive)			
Bit 6	10	SDRAM4 (Active/Inactive)			
Bit 5		Reserved, drive to 0			
Bit 4		Reserved, drive to 0			
Bit 3	7	SDRAM3 (Active/Inactive)			
Bit 2	6	SDRAM2 (Active/Inactive)			
Bit 1	3	SDRAM1 (Active/Inactive)			
Bit 0	2	SDRAM0 (Active/Inactive)			

Byte 1: SDRAM Active/Inactive Register (1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description	
Bit 7	27	SDRAM11 (Active/Inactive)	
Bit 6	26	SDRAM10 (Active/Inactive)	
Bit 5	23	SDRAM9 (Active/Inactive)	
Bit 4	22	SDRAM8 (Active/Inactive)	
Bit 3		Reserved, drive to 0	
Bit 2		Reserved, drive to 0	
Bit 1	19	SDRAM7 (Active/Inactive)	
Bit 0	18	SDRAM6 (Active/Inactive)	

Byte 2: SDRAM Active/Inactive Register (1 = Active, 0 = Inactive), Default = Active

Bit	Pin #	Description	
Bit 7		Reserved, drive to 0	
Bit 6	12	SDRAM12 (Active/Inactive)	
Bit 5		Reserved, drive to 0	
Bit 4		Reserved, drive to 0	
Bit 3		Reserved, drive to 0	
Bit 2		Reserved, drive to 0	
Bit 1		Reserved, drive to 0	
Bit 0		Reserved, drive to 0	



Maximum Ratings

Supply Voltage to Ground Potential0.5V to +7.0V	/
DC Input Voltage (Except BUF_IN)0.5V to V _{DD} + 0.5V	/
DC Input Voltage (BUF_IN)0.5V to +7.0V	I
Storage Temperature65°C to +150°C)

Max. Soldering Temperature (10 sec.)	260°C
Junction Temperature	150°C
Static Discharge Voltage (per MIL-STD-883, Method 3015)>	>2000V

Operating Conditions^[1]

Parameter	Description	Min.	Max.	Unit
V _{DD}	Supply Voltage	3.135	3.465	V
T _A	Operating Temperature (Ambient Temperature)	0	70	°C
CL	Load Capacitance		30	pF
C _{IN}	Input Capacitance		7	pF

Electrical Characteristics Over the Operating Range

Parameter	Description	Test Conditions	Min.	Max.	Unit
V _{IL}	Input LOW Voltage ^[2]	Except I ² C pins		0.8	V
V _{ILiic}	Input LOW Voltage	For I ² C pins only		0.7	V
V _{IH}	Input HIGH Voltage ^[2]		2.0		V
IIL	Input LOW Current (BUF_IN input)	V _{IN} = 0V	-10	10	μΑ
IIL	Input LOW Current (Except BUF_IN Pin)	V _{IN} = 0V		100	μΑ
I _{IH}	Input HIGH Current	$V_{IN} = V_{DD}$	-10	10	μA
V _{OL}	Output LOW Voltage ^[3]	I _{OL} = 25 mA		0.4	V
V _{OH}	Output HIGH Voltage ^[3]	I _{OH} = -36 mA	2.4		V
I _{DD}	Supply Current ^[3]	Unloaded outputs, 100 MHz		200	mA
I _{DD}	Supply Current ^[3]	Loaded outputs, 100 MHz		290	mA
I _{DD}	Supply Current ^[3]	Unloaded outputs, 66.67 MHz		150	mA
I _{DD}	Supply Current ^[3]	Loaded outputs, 66.67 MHz		185	mA
I _{DDS}	Supply Current	BUF_IN=V _{DD} or V _{SS} All other inputs at V _{DD}		500	μΑ

Notes:

Electrical parameters are guaranteed under the operating conditions specified.
BUF_IN input has a threshold voltage of V_{DD}/2.
Parameter is guaranteed by design and characterization. Not 100% tested in production.



Switching Characteristics^[4] Over the Operating Range

Parameter	Name	Test Conditions	Min.	Тур.	Max.	Unit
	Maximum Operating Frequency				100	MHz
	Duty Cycle ^[3,5] = $t_2 \div t_1$	Measured at 1.5V	45.0	50.0	55.0	%
t ₃	Rising Edge Rate ^[3]	Measured between 0.4V and 2.4V	0.9	1.5	4.0	V/ns
t ₄	Falling Edge Rate ^[3]	Measured between 2.4V and 0.4V	0.9	1.5	4.0	V/ns
t ₅	Output to Output Skew ^[3]	All outputs equally loaded	-250		+250	ps
t ₆	SDRAM Buffer LH Prop. Delay ^[3]	Input edge greater than 1V/ns	1.0	3.5	5.0	ns
t ₇	SDRAM Buffer HL Prop. Delay ^[3]	Input edge greater than 1V/ns	1.0	3.5	5.0	ns
t ₈	SDRAM Buffer Enable Delay ^[3]	Input edge greater than 1V/ns	1.0	5	12	ns
t ₉	SDRAM Buffer Disable Delay ^[3]	Input edge greater than 1V/ns	1.0	20	30	ns

Notes:

All parameters specified with loaded outputs.
Duty cycle of input clock is 50%. Rising and falling edge rate of the input clock is greater than 1V/ns.

Switching Waveforms

Duty Cycle Timing



All Outputs Rise/Fall Time



Output-Output Skew





Switching Waveforms (continued)

SDRAM Buffer LH and HL Propagation Delay



SDRAM Buffer Enable and Disable Times



Test Circuit





Application Information

Clock traces must be terminated with either series or parallel termination, as they are normally done.

Application Circuit



Summary

- Surface mount, low-ESR, ceramic capacitors should be used for filtering. Typically, these capacitors have a value of 0.1 μF. In some cases, smaller value capacitors may be required.
- The value of the series terminating resistor satisfies the following equation, where Rtrace is the loaded characteristic impedance of the trace, Rout is the output impedance of the buffer (typically 25Ω), and Rseries is the series terminating resistor. Rseries > Rtrace – Rout
- Footprints must be laid out for optional EMI-reducing capacitors, which should be placed as close to the terminating resistor as is physically possible. Typical values of these capacitors range from 4.7 pF to 22 pF.
- A Ferrite Bead **may** be used to isolate the Board V_{DD} from the clock generator V_{DD} island. Ensure that the Ferrite Bead offers greater than 50 Ω impedance at the clock frequency, under loaded DC conditions. Please refer to the application note "Layout and Termination Techniques for Cypress Clock Generators" for more details.
- If a Ferrite Bead is used, a 10 μF–22 μF tantalum bypass capacitor should be placed close to the Ferrite Bead. This capacitor prevents power supply droop during current surges.

Ordering Information

Ordering Code	Package Name	Package Type	Operating Range
CY2313ANZSC-1	S21	28-Pin SOIC	Commercial

Document #: 38-00692-A



Package Diagram



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